

Global and United States Solder Ball Market Research by Company, Type & Application 2013-2025

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Abstracts

SUMMARY

In integrated circuit packaging, a solder ball, also a solder bump (often referred to simply as 'ball' or 'bumps') is a ball of solder that provides the contact between the chip package and the printed circuit board, as well as between stacked packages in multichip modules. The Solder Ball can be placed manually or by automated equipment, and are held in place with a tacky flux.

Market Segment as follows:

By Type

Lead Solder Ball

Lead Free Solder Ball

By Application

BGA

CSP & WLCSP

Flip-Chip & Others

By Company

Senju Metal

DS HiMetal

MKE

YCTC

Nippon Micrometal

Accurus

PMTC

Shanghai hiking solder material

Shenmao Technology

The main contents of the report including:

Section 1:

Product definition, type and application, global and United States market overview;

Section 2:

Global and United States Market competition by company;

Section 3:

Global and United States sales revenue, volume and price by type;

Section 4:

Global and United States sales revenue, volume and price by application;

Section 5:

United States export and import;

Section 6:

Company information, business overview, sales data and product specifications;

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